



FEATURES:

- Bus switches provide zero delay paths
- Extended commercial range of -40°C to +85°C
- Low switch on-resistance
- TTL-compatible input and output levels
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- Available in QSOP, SOIC, SSOP, TSSOP, and PDIP Packages
- Hot insertion capability
- Very low power dissipation

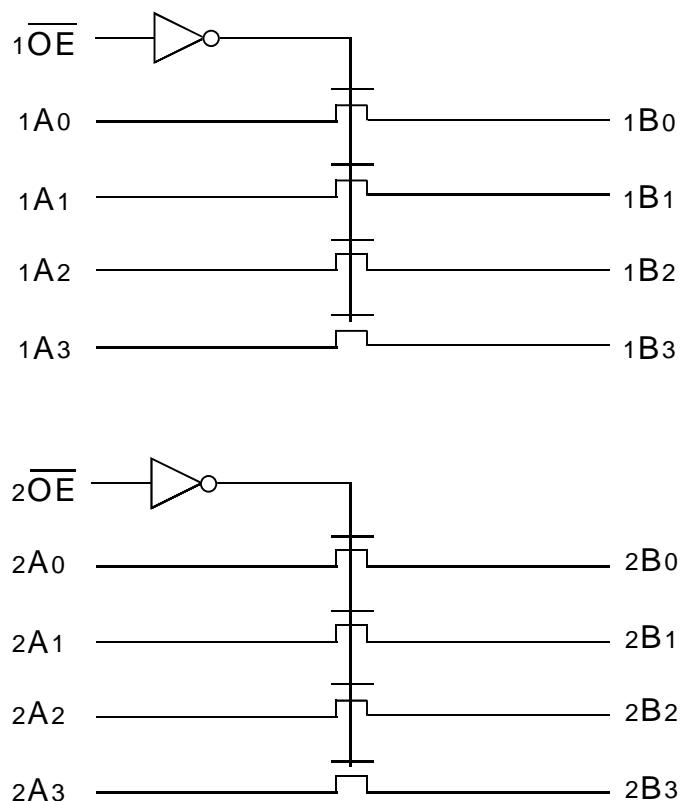
DESCRIPTION:

The FST3244 belongs to IDT's family of Bus switches. Bus switch devices perform the function of connecting or isolating two ports without providing any inherent current sink or source capability. Thus they generate little or no noise of their own while providing a low resistance path for an external driver. These devices connect input and output ports through an n-channel FET. When the gate-to-source junction of this FET is adequately forward-biased the device conducts or the resistance between input and output ports is small. Without adequate bias on the gate-to-source junction of the FET, the FET is turned off, therefore with no Vcc applied, the device has hot insertion capability.

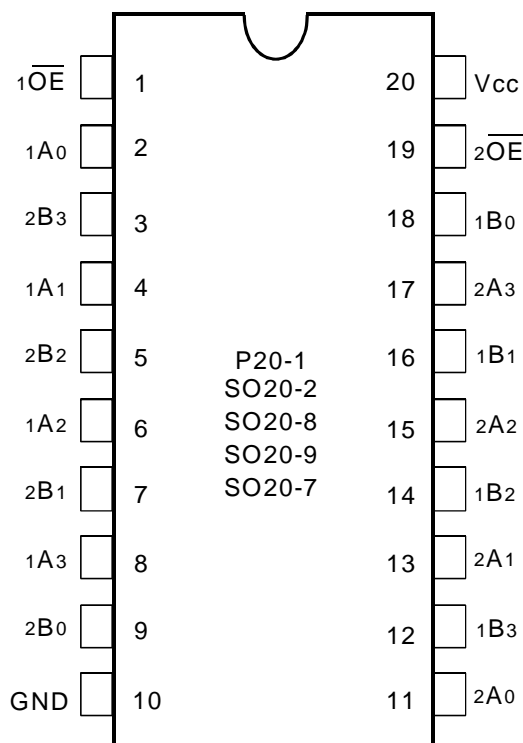
The low on-resistance and simplicity of the connection between input and output ports reduces the delay in this path to close to zero.

The FST3244 is an octal TTL-compatible bus switch. The \overline{OE} pins provide output enable control for all 8 bits. This device is pin-compatible with and functionally similar to the FCT244T.

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATION



QSOP/ SOIC/ SSOP/ TSSOP/ PDIP
TOP VIEW

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Rating	Max.	Unit
VTERM(2)	Terminal Voltage with Respect to GND	-0.5 to +7	V
TSTG	Storage Temperature	-65 to +150	°C
IOUT	Maximum Continuous Channel Current	128	mA

FST LINK

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- Vcc, Control, and Switch terminals.

CAPACITANCE (1)

Symbol	Parameter	Conditions(2)	Typ.	Unit
CIN	Control Input Capacitance		8	pF
C _{I/O}	Switch Input/Output Capacitance	Switch Off	13	pF

NOTES:

- Capacitance is characterized but not tested.
- TA = 25°C, f = 1MHz, VIN = 0V, VOUT = 0V

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Conditions: TA = -40°C to +85°C, Vcc = 5.0V ±5%

Symbol	Parameter	Test Conditions	Min.	Typ.(1)	Max.	Unit
VIH	Control Input HIGH Voltage	Guaranteed Logic HIGH Level	2	—	—	V
VIL	Control Input LOW Voltage	Guaranteed Logic LOW Level	—	—	0.8	V
I _{IH}	Control Input HIGH Current	Vcc = Max. VI = Vcc VI = GND	—	—	±1	μA
I _{IL}	Control Input LOW Current		—	—	±1	μA
I _{ozH}	Current during	Vcc = Max., Vo = 0 to 5V	—	—	±1	μA
I _{ozL}	Bus Switch DISCONNECT		—	—	±1	μA
V _{IK}	Clamp Diode Voltage	Vcc = Min., I _{IN} = -18mA	—	-0.7	-1.2	V
I _{OFF}	Switch Power Off Leakage	Vcc = 0V, VIN or Vo ≤ 5.5V	—	—	±1	μA
I _{CC}	Quiescent Power Supply Current	Vcc = Max., VIN = GND or Vcc	—	0.1	3	μA

BUS SWITCH IMPEDANCE OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Conditions: TA = -40°C to +85°C, Vcc = 5.0V ±5%

Symbol	Parameter	Test Conditions	Min.	Typ.(1)	Max.	Unit
RON	Switch CONNECT Resistance, A to B(2)	Vcc = Min., VIN = 0V ION = 30mA	—	5	7	Ω
		Vcc = Min., VIN = 2.4V ION = 15mA	—	10	15	
I _{OS}	Short Circuit Current, A to B(3)	A(B) = 0V, B(A) = Vcc	100	—	—	mA

NOTES:

- Typical values are at Vcc = 5.0V, +25°C ambient.
- The voltage drop between the indicated ports divided by the current through the switch.
- Not more than one output should be shorted at one time. Duration of the test should not exceed one second.

PIN DESCRIPTION

Pin Names	Description
xOE	Output Enable Inputs (Active LOW)
xAx	A Port Bits
xBx	B Port Bits

FUNCTION TABLE (1)

1OE	2OE	Description
H	H	Disconnect
L	H	Connect 1A to 1B
H	L	Connect 2A to 2B
L	L	Connect 1A to 1B and 2A to 2B

NOTE:

- H = HIGH
L = LOW

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
ΔI_{CC}	Quiescent Power Supply Current TTL Inputs HIGH	$V_{CC} = \text{Max.}$ $V_{IN} = 3.4V^{(3)}$		—	0.5	1.5	mA
I_{CCD}	Dynamic Power Supply Current ⁽⁴⁾	$V_{CC} = \text{Max.}$ Outputs Open 1 Enable Pin Toggling 50% Duty Cycle	$V_{IN} = V_{CC}$ $V_{IN} = GND$	—	120	160	$\mu A/$ MHz/ Enable
I_C	Total Power Supply Current ⁽⁶⁾	$V_{CC} = \text{Max.}$ Outputs Open 2 Enable Pins Toggling $f_i = 10\text{MHz}$ 50% Duty Cycle	$V_{IN} = V_{CC}$ $V_{IN} = GND$	—	2.4	3.2	mA
			$V_{IN} = 3.4$ $V_{IN} = GND$	—	2.9	4.7	

NOTES:

- For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- Typical values are at $V_{CC} = 3.3V$, $+25^\circ C$ ambient.
- Per TTL driven input ($V_{IN} = 3.4V$). All other inputs at V_{CC} or GND .
- This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- $CPD = I_{CCD}/V_{CC}$
CPD = Power Dissipation Capacitance
- $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
 $I_C = I_{CC} + \Delta I_{CC} \cdot DH_{NT} + I_{CCD} \cdot (f_i N)$
I_{CC} = Quiescent Current
 ΔI_{CC} = Power Supply Current for a TTL High Input ($V_{IN} = 3.4V$)
DH = Duty Cycle for TTL Inputs High
NT = Number of TTL Inputs at DH
I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
 f_i = Input Frequency
N = Number of Switches Toggling at f_i
All currents are in milliamps and all frequencies are in megahertz.

SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Conditions: $T_A = -40^\circ C$ to $+85^\circ C$, $V_{CC} = 5.0V \pm 5\%$

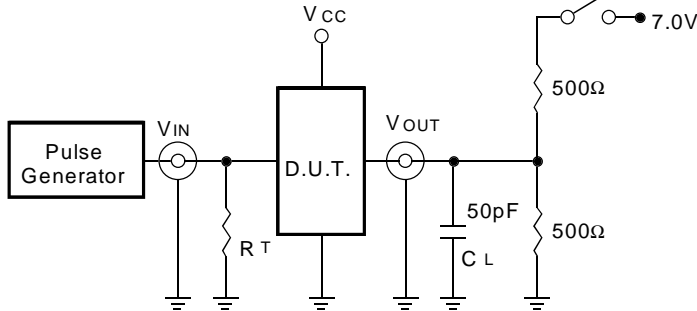
Symbol	Description	Min. ⁽²⁾	Typ.	Max.	Unit
t_{PLH} t_{PHL}	Data Propagation Delay A to B, B to A ⁽²⁾	—	—	0.25	ns
t_{PZH} t_{PZL}	Switch CONNECT Delay \overline{xOE} to A or B	1.5	—	6.5	ns
t_{PHZ} t_{PLZ}	Switch DISCONNECT Delay \overline{xOE} to A or B	1.5	—	5.5	ns
$ Q_{CI} $	Charge Injection During Switch DISCONNECT, \overline{xOE} to A or B ⁽³⁾	—	1.5	—	pC

NOTES:

- See test circuit and waveforms.
- The bus switch contributes no propagation delay other than the RC delay of the load interacting with the RC of the switch.
- IQ_{CI} is the charge injection for a single switch DISCONNECT and applies to either single switches or multiplexers.
 IQ_{DCI} is the charge injection for a multiplexer as the multiplexed port switches from one path to another. Charge Injection is reduced because the injection from the DISCONNECT of the first path is compensated by the CONNECT of the second path.

TEST CIRCUITS AND WAVEFORMS

TEST CIRCUITS FOR ALL OUTPUTS



SWITCH POSITION

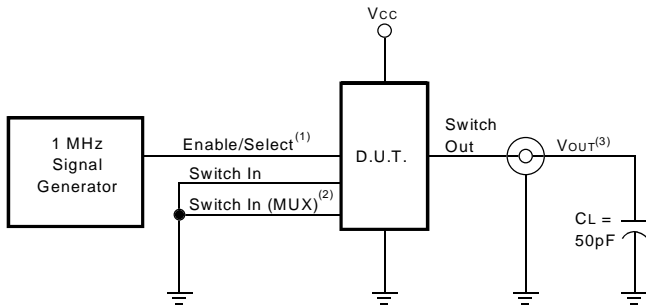
Test	Switch
Open Drain	Closed
Disable Low	
Enable Low	
All Other Tests	Open

FCT LINK

DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.
RT = Termination resistance: should be equal to ZOUT of the Pulse Generator.

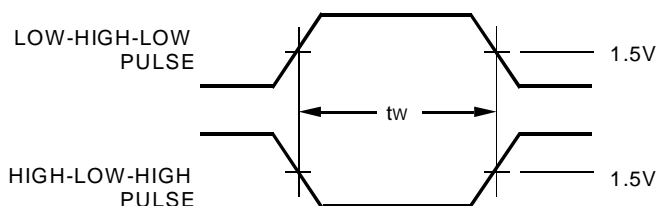
CHARGE INJECTION



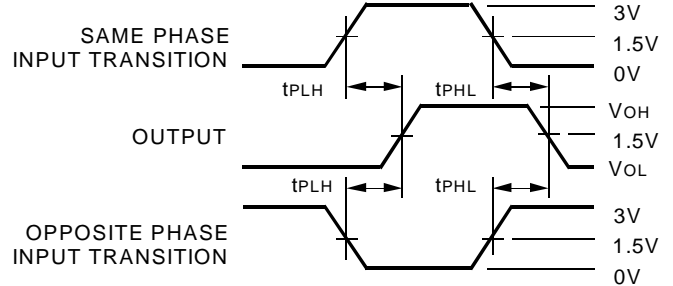
NOTES:

- Select is used with multiplexers for measuring IQDCIL during multiplexer select. During all other tests Enable is used.
- Used with multiplexers to measure IQDCIL only.
- Charge Injection = $\Delta V_{OUT} C_L$, with Enable toggling for IQCIL or Select toggling for IQDCIL. ΔV_{OUT} is the change in VOUT and is measured with a 10MΩ probe.

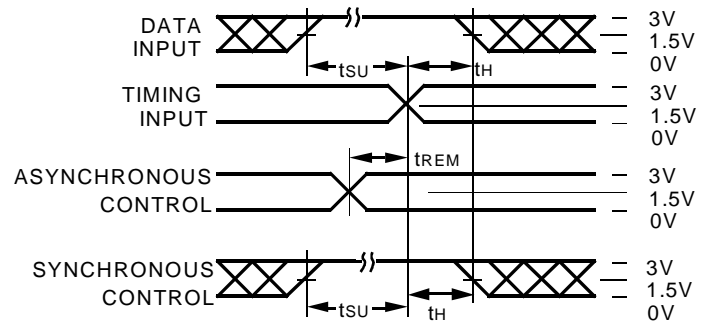
PULSE WIDTH



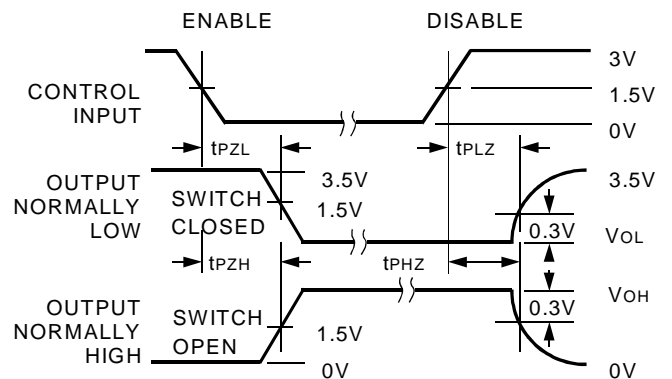
PROPAGATION DELAY



SET-UP, HOLD, AND RELEASE TIMES



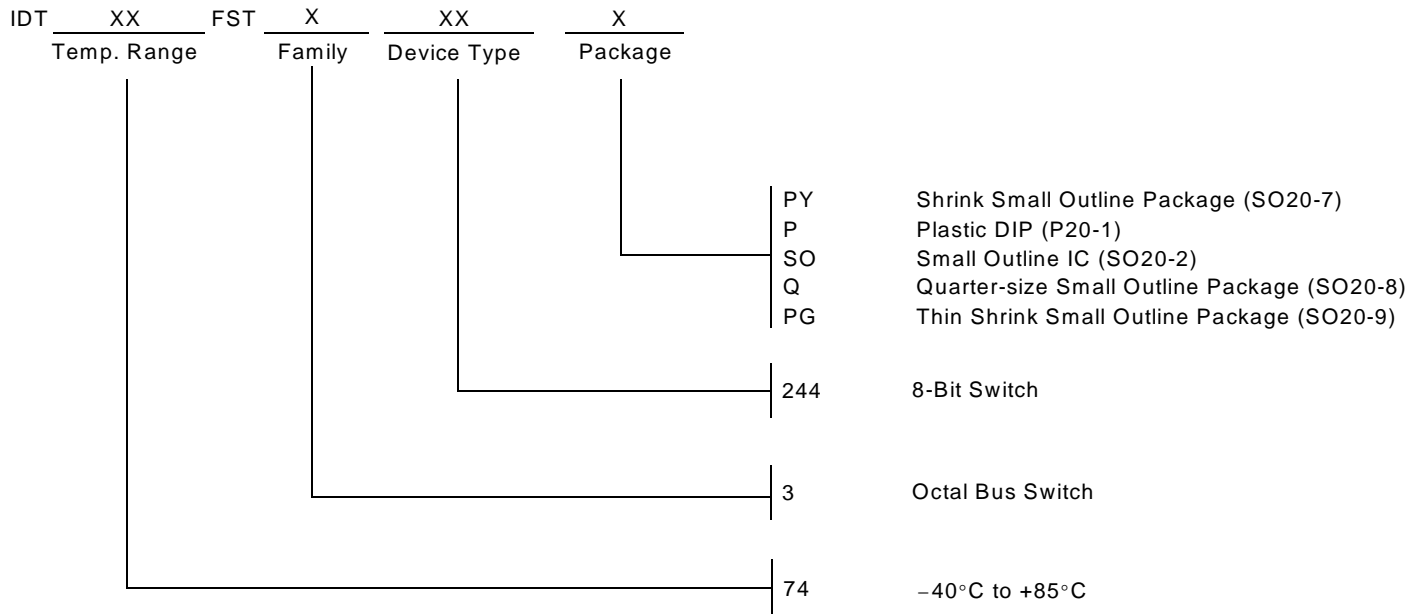
ENABLE AND DISABLE TIMES



NOTES:

- Diagram shown for input Control Enable-LOW and input Control Disable-HIGH
- Pulse Generator for All Pulses: Rate $\leq 1.0\text{MHz}$; $t_f \leq 2.5\text{ns}$; $t_r \leq 2.5\text{ns}$

ORDERING INFORMATION



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